

8th "Trento" Workshop on Advanced Silicon Radiation Detectors (3D and p-type)

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3D-S: A fast, high resolution, low-mass, detector with embedded cooling and internal charge multiplication capability

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3D silicon sensors have completed the key milestones set by the 3DATLAS R&D collaboration and are now industrially fabricated. A new challenge is now being faced for the HL-LHC which will require a totally new approach in sensor fabrication. 3DS is an innovative fast, low mass modular system where all components, including cooling and active edges, are fabricated and are vertically integrated using microfabrication techniques. The talk will present some of the highlights of the current 3D sensors production and discuss the development status of 3DS.

Primary authors: LAI, Ching Hung (The University of Manchester, UK); Dr DA VIA, Cinzia (University of Manchester (GB)); Prof. DALLA BETTA, Gian-Franco (INFN and University of Trento); POVOLI, Marco (University of Trento (Italy))

Co-authors: MAPELLI, Alessandro (CERN); KENNEY, Chris (SLAC); ROMAGNOLI, Giulia (Universita e INFN (IT)); PELLEGRINI, Giulio (Universidad de Valencia (ES)); BOSCARDIN, Maurizio (FBK Trento); PETAGNA, Paolo (CERN); GRENIER, Philippe Jean-Paul (SLAC National Accelerator Laboratory (US)); GRINSTEIN, Sebastian (IFAE/ICREA - Barcelona); PARKER, Sherwood Ira (University of Hawai'i at Manoa (US))

Presenter: Dr DA VIA, Cinzia (University of Manchester (GB))

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